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## ABSTRACT

A packaging structure of an image sensor includes a substrate, an image sensing chip, a plurality of wirings, and a transparent layer. The substrate includes a plurality of metal sheets, glue for sealing the metal sheets, a first surface, and a second surface. The metal sheets are exposed to the outside via the first surface and the second surface to form first contacts and second contacts, respectively. The image sensing chip is mounted on the substrate. The plurality of bonding pads are formed on the image sensing chip. The plurality of wirings electrically connect the bonding pads on the image sensing chip to the first contacts of the first surface of the substrate, in order to electrically connect the image sensing chip to the substrate. The transparent layer is arranged above the image sensing chip. Therefore, a packaging structure of an image sensor made of plastic materials can be formed, thereby simplifying the packaging processes and lowering the manufacturing costs.

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